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**ON Semiconductor**<sup>®</sup>

# FCA20N60 N-Channel SuperFET<sup>®</sup> MOSFET 600 V, 20 A, 190 mΩ

# Features

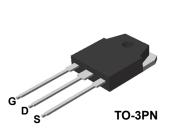
- 650V @ T<sub>J</sub> = 150°C
- Typ. R<sub>DS(on)</sub> = 150 mΩ
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 75 nC )
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 165 pF )
- 100% Avalanche Tested

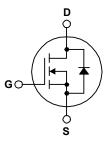
#### Applications

- Solar Inverter
- AC-DC Power Supply

# Description

SuperFET<sup>®</sup> MOSFET is ON Semiconductor's first genera-tion of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.





#### MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter			FCA20N60 / FCA20N60-F109	Unit	
V <sub>DSS</sub>	Drain to Source Voltage	Drain to Source Voltage			V	
V <sub>GSS</sub>	Gate-Soure voltage			±30	V	
	Drain Current	- Continuous (T <sub>C</sub> = 25 <sup>o</sup> C)		20	^	
D	DrainCurrent	- Continuous (T <sub>C</sub> = 100 <sup>o</sup> C)		12.5	- A	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	60	А	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		(Note 2)	690	mJ	
I <sub>AR</sub>	Avalanche Current		(Note 1)	20	А	
E <sub>AR</sub>	Repetitive Avalanche Energy		(Note 1)	20.8	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note		(Note 3)	4.5	V/ns	
P <sub>D</sub>	Dowen Dissingtion	(T <sub>C</sub> = 25°C)		208	W	
	Power Dissipation	- Derate Above 25 <sup>o</sup> C		1.67	W/ <sup>o</sup> C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300	°C	

### **Thermal Characteristics**

Symbol	Parameter	FCA20N60 / FCA20N60_F109	Unit
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.6	°C/W
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient, Max.	41.7	0/00

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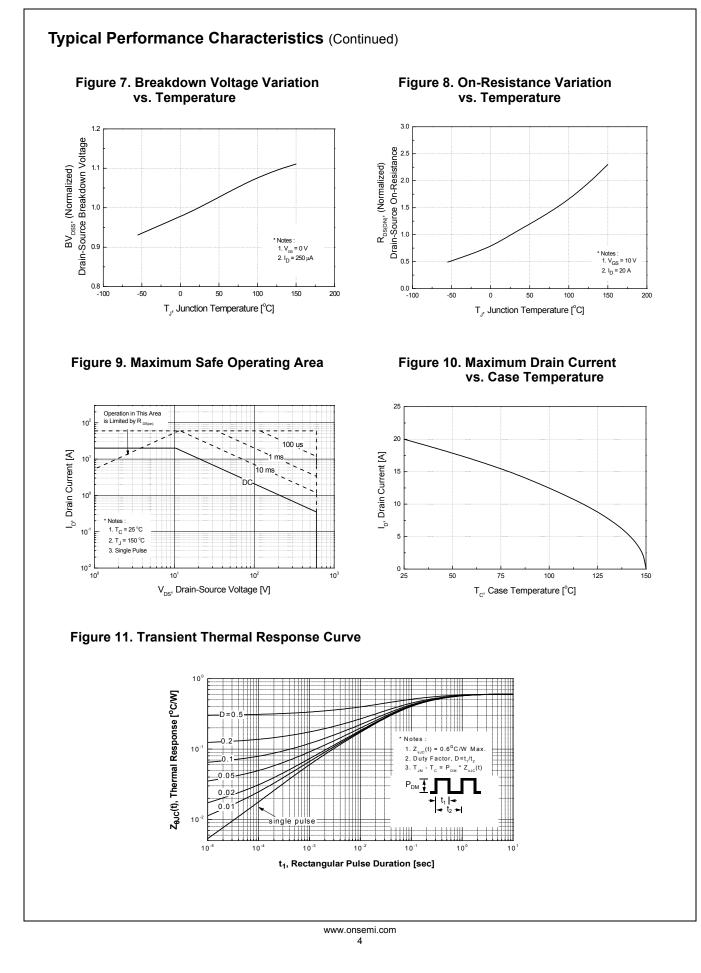
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FCA20N60
N-Channel
SuperFET <sup>®</sup>
MOSFET

Part Nun	nber	Top Mark	Package	Packing Method	Reel Size	Тар	e Width	Qua	ntity
FCA20N60		FCA20N60	TO-3PN	Tube	N/A	N/A N/A		30 units 30 units	
FCA20N60-F109 FCA		FCA20N60	TO-3PN	Tube	N/A				
Electrica	l Chara	acteristics T <sub>C</sub> =	25 <sup>o</sup> C unless o	therwise noted.					
Symbol	nbol Parameter			Test Conditions		Min.	Тур.	Max.	Unit
Off Charac	teristics	;							
BV <sub>DSS</sub>	Drain to	n to Source Breakdown Voltage		$I_D$ = 250 µA, $V_{GS}$ = 0 V, $T_J$ = 25°C		600	-	-	V
				$I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 150^{\circ}C$		-	650	-	V
ΔΒV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdov	eakdown Voltage Temperature pefficient		$I_D$ = 250 $\mu$ A, Referenced to 25°C		-	0.6	-	V/ºC
BV <sub>DS</sub>	Drain-Source Avalanche Breakdown Voltage		down ۱	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 20 A		-	700	-	V
1	Zoro Cot			V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-		1	
DSS	Zero Gal	e Voltage Drain Curre	\ \	/ <sub>DS</sub> = 480 V, T <sub>C</sub> = 125 <sup>c</sup>		-	-	10	μA
I <sub>GSS</sub>	Gate to Body Leakage Current $V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$			/	-	-	±100	nA	
On Charac	teristics	j.							
V <sub>GS(th)</sub>	Gate Thr	reshold Voltage	١	$V_{GS} = V_{DS}, I_{D} = 250 \ \mu A$		3.0	-	5.0	V
R <sub>DS(on)</sub>	Static Dra	ain to Source On Resi		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		-	0.15	0.19	Ω
9 <sub>FS</sub>	Forward	ard Transconductance $V_{DS} = 40 \text{ V}, I_D = 10 \text{ A}$				-	17	-	S
Dynamic C	haracte	ristics							
C <sub>iss</sub>	Input Ca	pacitance				-	2370	3080	pF
C <sub>oss</sub>	Output C	apacitance		V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz		-	1280	1665	pF
C <sub>rss</sub>	Reverse	Transfer Capacitance	1			-	95	-	pF
C <sub>oss</sub>	Output Capacitance			$V_{DS}$ = 480 V, $V_{GS}$ = 0 V, f = 1 MHz		-	65	85	pF
Coss(eff.)		Effective Output Capacitance		$V_{DS} = 0 V \text{ to } 400 V, V_{GS} = 0 V$ $V_{DS} = 480 V, I_D = 20 A,$		-	165	-	pF
Qg	Total Gate Charge at 10V					-	75	98	nC
Q <sub>gs</sub>		Source Gate Charge		$V_{GS} = 10 V$		-	13.5	18	nC
Q <sub>gd</sub>	Gate to L	Drain "Miller" Charge			(Note 4)	-	36	-	nC
Switching	Charact	eristics							
t <sub>d(on)</sub>	Turn-On Delay Time					-	62	135	ns
t <sub>r</sub>	Turn-On	Rise Time		/ <sub>DD</sub> = 300 V, I <sub>D</sub> = 20 A,	,	-	140	290	ns
t <sub>d(off)</sub>		Delay Time	\\	$/_{\rm GS}$ = 10 V, R <sub>G</sub> = 25 Ω	()()	-	230	470	ns
t <sub>f</sub>	Turn-Off	Fall Time			(Note 4)	-	65	140	ns
Drain-Soui	ce Diod	e Characteristics	;						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current				-	-	20	Α	
I <sub>SM</sub>		n Pulsed Drain to Sour				-	-	60	A
V <sub>SD</sub>		Source Diode Forward		V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 20 A		-	-	1.4	V
t <sub>rr</sub>		Recovery Time		$I_{\rm GS} = 0  \text{V},  I_{\rm SD} = 20  \text{A},$	_	-	530	-	ns
Q <sub>rr</sub>	Reverse	Recovery Charge	C	ll <sub>F</sub> /dt = 100 A/μs		-	10.5	-	μC

#### **Typical Performance Characteristics** Figure 1. On-Region Characteristics **Figure 2. Transfer Characteristics** 10<sup>2</sup> 10<sup>2</sup> •<sub>GS</sub> 15.0 V Тор 10.0 V 8.0 V 7.0 V I<sub>D</sub>, Drain Current [A] 6.5 V I<sub>b</sub>, Drain Current [A] 6.0 V 10 55 V 150°C Po 10 25°0 -55°C 10 10<sup>0</sup> \* Note 1. V<sub>DS</sub> = 40V \* No 1. 250µs Pulse -----2. 250µs Pulse Test 2. T<sub>C</sub> = 25<sup>0</sup>C 2 4 6 8 10 10<sup>-1</sup> 10<sup>0</sup> 10<sup>1</sup> $\mathsf{V}_{_{\mathrm{GS}}}$ , Gate-Source Voltage [V] V<sub>DS</sub>, Drain-Source Voltage [V] Figure 4. Body Diode Forward Voltage Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage** Variation vs. Source Current and Temperatue 10 0.4 ₹ R<sub>DS(ON)</sub> [Ω], Drain-Source On-Resistance 10 8 l<sub>DR</sub> , Reverse Drain Current = 10V V<sub>G</sub> 10<sup>1</sup> = 20V V 150°C 25°C 10<sup>0</sup> <sup>r</sup> Notes : 1. V<sub>GS</sub> = 0V 2. 250µs Pulse Test \* Note : T<sub>J</sub> = 25<sup>0</sup>C 0.0 55 60 65 70 0 5 10 15 20 25 30 35 40 45 50 0.2 0.4 0.6 0.8 1.0 1.2 1.4 1.6 $\rm V_{_{SD}}$ , Source-Drain Voltage $\,[V]$ I<sub>D</sub>, Drain Current [A] **Figure 5. Capacitance Characteristics Figure 6. Gate Charge Characteristics** 10000 12 $C_{iss} = C_{gs} + C_{gd} (C_{ds} = shorted)$ $C_{oss} = C_{ds} + C_{gd}$ V<sub>DS</sub> = 100V 9000 V<sub>DS</sub> = 250V C\_ C 8000 $V_{_{\rm GS}}$ , Gate-Source Voltage [V] V<sub>DS</sub> = 400V 7000 Capacitance [pF] 6000 5000 6 Notes : 1. V<sub>GS</sub> = 0 V 4000 2. f = 1 MHz 3000 2000 1000 \* Note : I<sub>D</sub> = 20A 0 0 10-1 10<sup>0</sup> 10<sup>1</sup> 0 10 20 30 40 50 60 70 80 V<sub>DS</sub>, Drain-Source Voltage [V] Q<sub>G</sub>, Total Gate Charge [nC]

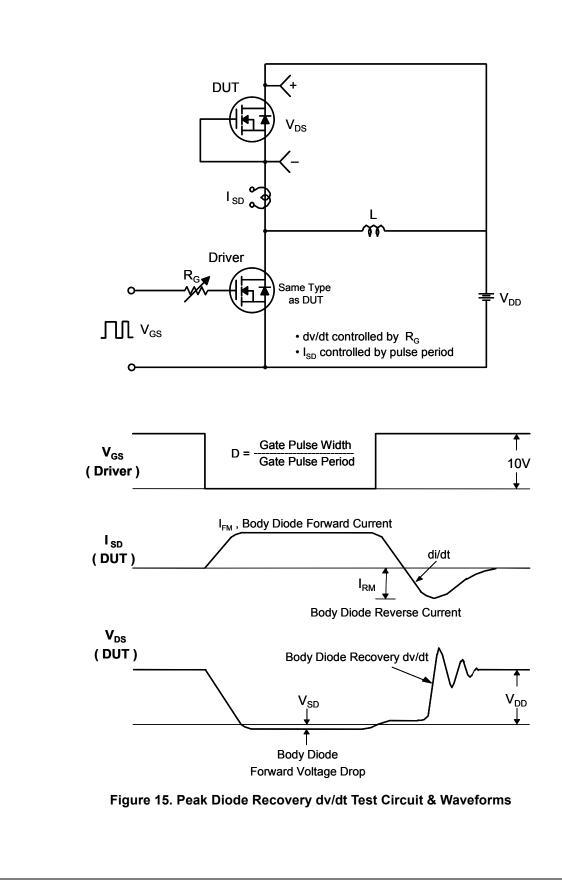
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 $V_{GS}$ ξ R  $\mathsf{Q}_\mathsf{g}$ V<sub>DS</sub>  $\mathsf{Q}_{\mathsf{gd}}$  $\mathsf{Q}_{\mathsf{gs}}$ •17 DUT I<sub>G</sub> = const. Charge Figure 12. Gate Charge Test Circuit & Waveform R VDS VDS 90% V<sub>DD</sub> V<sub>GS</sub>  $\mathsf{R}_{\mathsf{G}}$ 10% V<sub>GS</sub> V<sub>GS</sub> ∏ DUT 0 Figure 13. Resistive Switching Test Circuit & Waveforms  $E_{AS} = \frac{1}{2} L I_{AS}^2 \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$ L VDS  $\mathsf{BV}_{\mathsf{DSS}}$ ID o  $I_{AS}$  $\mathsf{R}_\mathsf{G}$ = V<sub>DD</sub>  $I_{D}(t)$ V<sub>GS</sub>  $V_{\text{DD}}$ V<sub>DS</sub>(t) DUT Time t, Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

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